

NGP300 Non-Silicone Gap Pad

NGP300 is a non-silicone, thermally conductive material for use at a thermal interface. Excellent properties are obtained from NGP300 due to the use of metal oxide powders. NGP300 is electrically insulative.

- Silicone free with two natural tack sides for easy handling
- Good thermal conductivity; 3.0 W/m.K
- Good flexibility, strength and high elastic resilience
- Flame retardant; meets UL94 V-0

Approvals	RoHS-2 Compliant (2015/863/EU): UL Approval:	Yes Meets UL94 V-0
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Typical Properties	Colour:	Grey
	Density @ 20°C (g/ml):	2.9
	Thickness (mm)	0.5 – 1.0
	Hardness (Shore C)	35
	Tensile Strength (MPa):	0.17
	Thermal Conductivity:	3.0 W/m.K
	Temperature Range:	-40°C to +140°C
	Thermal Resistance (°C.in ² /W):	0.61
	Elongation (%):	243
	Volume Resistivity (Ω·cm):	7.4 x 10 ¹¹
	Dielectric Strength (kV/mm):	12
	Dielectric Constant @1MHz:	8.48
	Dielectric Loss:	0.063
	Compression Ratio (% @ 50psi):	30
	Flame Retardancy	Meets UL94 V-0

<u>Description</u>	<u>Order Code</u>	<u>Dimension of Gap Pad</u>
<u>Gap Pad</u>	NGP300S	200 x 200 x 0.5 mm
<u>Gap Pad</u>	NGP300SL	200 x 200 x 1.0 mm

Revision 2: October 2017